

3A,200V Schottky Barrier Rectifier

Features

- Low leakage current
- Schottky barrier diode
- Low forward voltage drop
- Moisture sensitivity: level 1, per J-STD-020
- Halogen-free according to IEC 61249-2-21 definition
- High temperature soldering guaranteed: 260 ℃/10 seconds



eSGB (DO-221AC)

Applications

For use in low voltage, high frequency inverters, free-wheeling and polarity protection application.

Maximum Ratings & Electrical Characteristics(TA=25°C unless otherwise noted)				
Parameter	Symbol	LS3C0	Unit	
Maximum repetitive peak reverse voltage	V _{RRM}	200	V	
Maximum RMS voltage	V _{RMS}	140	V	
Maximum DC blocking voltage	V _{DC}	200	V	
Maximum average forward rectified current	I _{F(AV)}	3	Α	
Peak forward surge current,8.3ms single half sine-wave superimposed on rated load per diode	IFSM	100	А	
Operating junction temperature range	TJ	-55 to +150	°C	
Storage temperature range	Тѕтс	-55 to +150	°C	

Thermal-Mechanical Specifications (TA=25°C unless otherwise noted)				
Parameter	Symbol	Тур	Unit	
Thermal Resistance, Junction to Ambient	Reja	85	°C /W	
Thermal Resistance, Junction to Case	Rejc	15	°C /W	
Thermal Resistance, Junction to Lead	R _{θJL}	18	°C /W	



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Electrical Specifications(TA=25°C unless otherwise noted)					
Parameter	Symbol	Test Conditions	Тур	Max	Unit
Forward Drop Voltage	V _F	I _F =3A	-	0.87	V
Reverse leakage current @V _R	IR	TJ =25°C	0.05		- mA
		T _J =125°C	10		
Typical junction capacitance	Сл	4.0 V 1 MHZ	69		pF

Note:

1. Mounted on copper pad area of 0.2x0.2" (5.0 x 5.0mm) to each terminal.





Ratings and Characteristics Curves

(TA = 25°C unless otherwise noted)

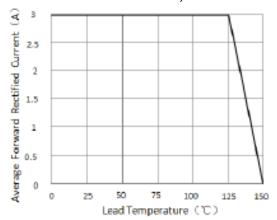


Figure 1.Forward Current Derating Curve

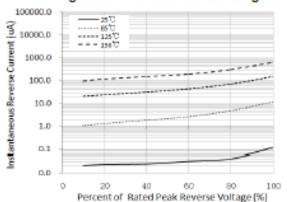


Figure 3. Typical Reverse Characteristics

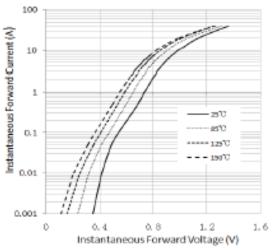


Figure 5. Typical Instantaneous Forward Characteristics

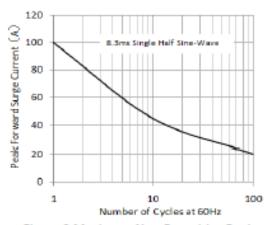


Figure 2.Maximum Non-Repetitive Peak Forward Surge Current

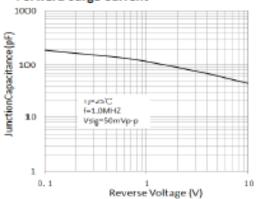


Figure 4. Typical Junction Capacitance

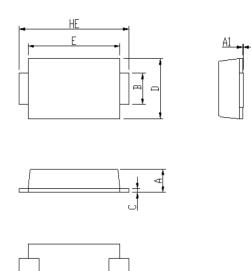




Package Outline Dimensions

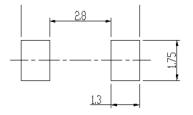
in inches (millimeters)

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DIM	Unit:	mm	Unit:	inch
	MIN	MAX	MIN	MAX
Α	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
В	1.25	1.45	0.049	0.057
С	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
Е	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



Revision History

Document Version	Date of release	Description of changes
Rev.A	2021.06.01	Released Datasheet
Rev.B	2023.10.12	Modify document format
Rev.C	2023.12.29	Modify package name





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